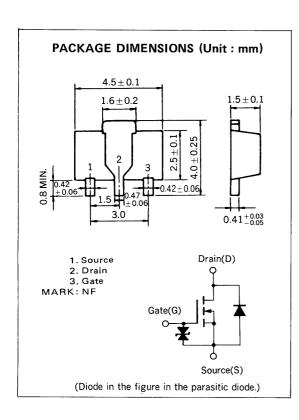


# MOS FIELD EFFECT TRANSISTOR **2SK1587**

# N-CHANNEL MOS FET FOR SWITCHING



The 2SK1587 is an N-channel vertical type MOS FET which can be driven by battery voltage (two dry cells).

As the MOS FET has on-state resistance and excellent switching characteristics, it is suitable for driving actuators such as motors, relays, and solenoids.

#### **FEATURES**

- Directly driven by ICs having a 3 V power supply.
- Has low on-state resistance

 $R_{DS(on)1} = 0.8 \Omega MAX$ . @  $V_{GS} = 2.5 V$ ,  $I_D = 0.5 A$  $R_{DS(on)2} = 0.5 \Omega MAX$ . @  $V_{GS} = 4.0 V$ ,  $I_D = 1.0 A$ 

#### **QUALITY GRADE**

Standard

Please refer to "Quality grade on NEC Semiconductor Devices" (Document number IEI-1209) published by NEC Corporation to know the specification of quality grade on the devices and its recommended applications.

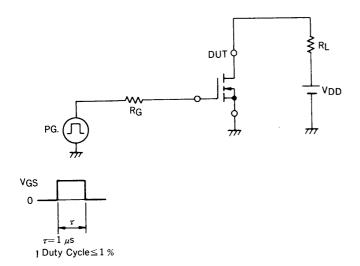
# ABSOLUTE MAXIMUM RATINGS ( $T_a = 25$ °C)

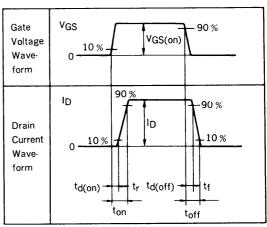
PARAMETER	SYMBOL	RATINGS	UNIT	TEST CONDITIONS
Drain to Source Voltage	V <sub>DSS</sub>	16	V	V <sub>GS</sub> = 0
Gate to Source Voltage	V <sub>GSS</sub>	±16	V	V <sub>DS</sub> = 0
Drain Current	ID(DC)	±2.0	А	
Drain Current	I <sub>D(pulse)</sub>	±4.0	Α	PW $\leq$ 10 ms, Duty Cycle $\leq$ 50 %
Total Power Dissipation	PT	2.0	w	When using ceramic board of 16 cm <sup>2</sup> x 0.7 mm
Channel Temperature	T <sub>ch</sub>	150	°C	
Storage Temperature	T <sub>stg</sub>	-55 to +150	°C	

# ELECTRICAL CHARACTERISTICS ( $T_a = 25$ °C)

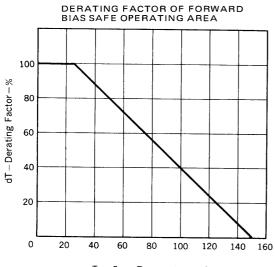
PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	TEST CONDITIONS
Drain Cut-off Current	IDSS			1.0	μΑ	V <sub>DS</sub> = 16 V, V <sub>GS</sub> = 0
Gate Leakage Current	IGSS			±5.0	μА	V <sub>GS</sub> = ±16 V, V <sub>DS</sub> = 0
Gate Cut-off Voltage	VGS(off)	8.0	1.2	1.6	V	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1.0 mA
Forward Transfer Admittance	ly <sub>fs</sub> l	0.4			S	V <sub>DS</sub> = 5.0 V, I <sub>D</sub> = 1.0 A
Drain to Source On-State Resistance	R <sub>DS</sub> (on)1		0.5	0.8	Ω	V <sub>GS</sub> = 2.5 V, I <sub>D</sub> = 0.5 A
Drain to Source On-State Resistance	R <sub>DS(on)2</sub>		0.3	0.5	Ω	V <sub>GS</sub> = 4.0 V, I <sub>D</sub> = 1.0 A
Input Capacitance	C <sub>iss</sub>		180		pF	
Output Capacitance	Coss		160		pF	V <sub>DS</sub> = 5.0 V, V <sub>GS</sub> = 0, f = 1 MHz
Feedback Capacitance	C <sub>rss</sub>		55		рF	1
Turn-On Delay Time	td(on)		100		ns	
Rise Time	t <sub>r</sub>		700		μs	$V_{DD}$ = 10 V, $I_{D}$ = 1.0 A $V_{GS(on)}$ = 3.0 V, $R_{G}$ = 10 $\Omega$ $R_{L}$ = 10 $\Omega$
Turn-Off Delay Time	td(off)		150		ns	
Fall Time	tf		200		ns	

# SWITCHING TIME MEASUREMENT CIRCUIT AND CONDITIONS

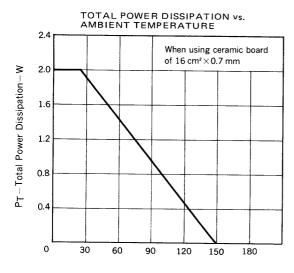




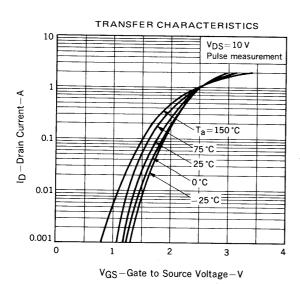
# TYPICAL CHARACTERISTICS (Ta = 25 °C)



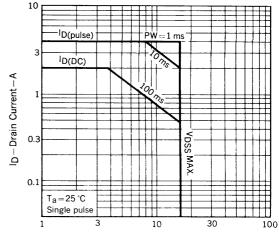




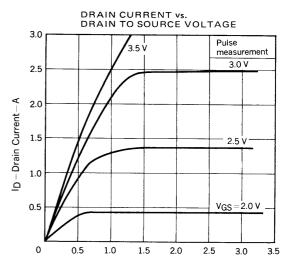
Ta-Ambient Temperature-°C



FORWARD BIAS SAFE OPERATING AREA

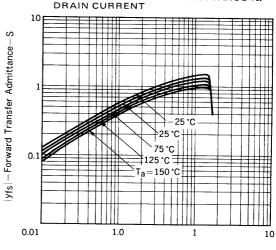


VDS-Drain to Source Voltage-V

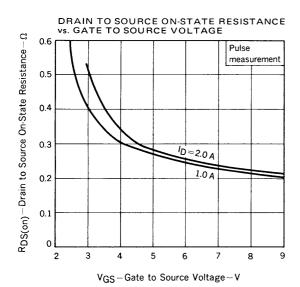


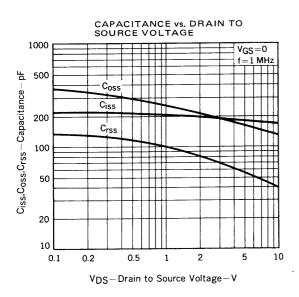
VDS-Drain to Source Voltage-V

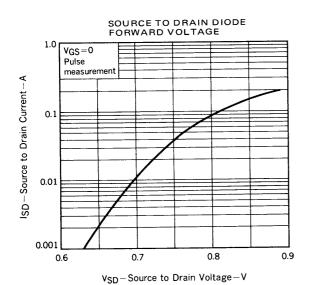
FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT

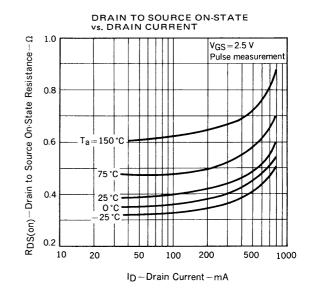


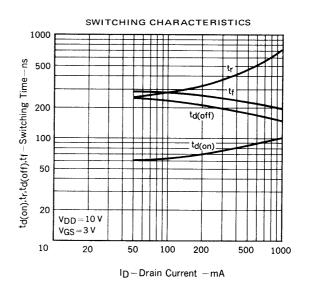
ID-Drain Current-A













# RECOMMENDED SOLDERING CONDITIONS

Mounting of this product by soldering should be done under the following conditions.

Please consult our representatives about soldering methods and conditions other than these.

# **SURFACE MOUNT TYPE**

For details of the recommended soldering conditions, see the information document "SMT MANUAL" (IEI-1207).

Soldering Method	Soldering Conditions	Symbol for Recommended Conditions
Infrared Reflow	Package peak temp.: 230 °C Soldering time: within 30 sec (above 210 °C) Soldering times: 1, Days limitation: none*	IR30-00
Vapor Phase Soldering	Package peak temp.: 215 °C Soldering time: within 40 sec (above 200 °C) Soldering times: 1, Days limitation: none*	VP15-00
Wave Soldering	Soldering bath temp.: below 260 °C Soldering time: within 10 sec Soldering times: 1, Days limitation: none*	WS60-00

 $<sup>\</sup>star$ : Stored days under storage conditions at 25  $^{\circ}$ C and below 65 % R.H. after the dry-pack has been opened.

Note 1 Combination of soldering methods should be avoided.

### REFERENCE

Document Name	Document No.	
NEC semiconductor device reliability/quality control system.	TEI-1202	
Quality grade on NEC semiconductor devices.	IEI-1209	
Semiconductor device mounting technology manual.	IEI-1207	
Semiconductor device package manual.	IEI-1213	
Guide to quality assurance for semiconductor devices.	MEI-1202	
Semiconductor selection guide.	MF-1134	

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